

C2225C332KFGACTU

Aliases (C2225C332KFGAC7800)

SMD Comm COG HV, Ceramic, 3,300 pF, 10%, 1,500 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 2225, 3.2 mm



Click [here](#) for the 3D model.

General Information

Series	SMD Comm COG HV
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	300 mg
Shelf Life	78 Weeks
MSL	1

Dimensions

Chip Size	2225
L	5.6mm +/-0.4mm
W	6.4mm +/-0.4mm
T	1.4mm +/-0.15mm
S	3.2mm MIN
B	0.6mm +/-0.35mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

Specifications

Capacitance	3,300 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	1500 VDC
Dielectric Withstanding Voltage	1,800 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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